

L Number	Hits	Search Text	DB	Time stamp
1	166	interposer near2 thickness	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 16:56
-	1	package and die and interposer and laminated adj conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:14
-	1	package and die and interposer and laminated near2 conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:14
-	308	package and die and interposer and conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:14
-	5	package and die and laminated adj conductor	USPAT	2003/09/11 14:51
-	6	package and die and laminated adj conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:52
-	19	package and chip and laminated adj conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 14:56
-	77	chip and laminated adj conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/11 15:23
-	13	("4513355" "4835120" "5043534" "5089878" "5220195" "5498901" "5548160" "5559306" "5629561" "5666003" "5672548" "5696033" "5767572").PN.	USPAT	2003/09/12 10:27
-	13	interposer same metal same organic adj material	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 14:47
-	22	(die or chip) same interposer same metal same organic	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 14:51
-	765	(die or chip) same interposer same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 14:52
-	348	(die or chip) same interposer same solder adj balls	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/09/29 16:55